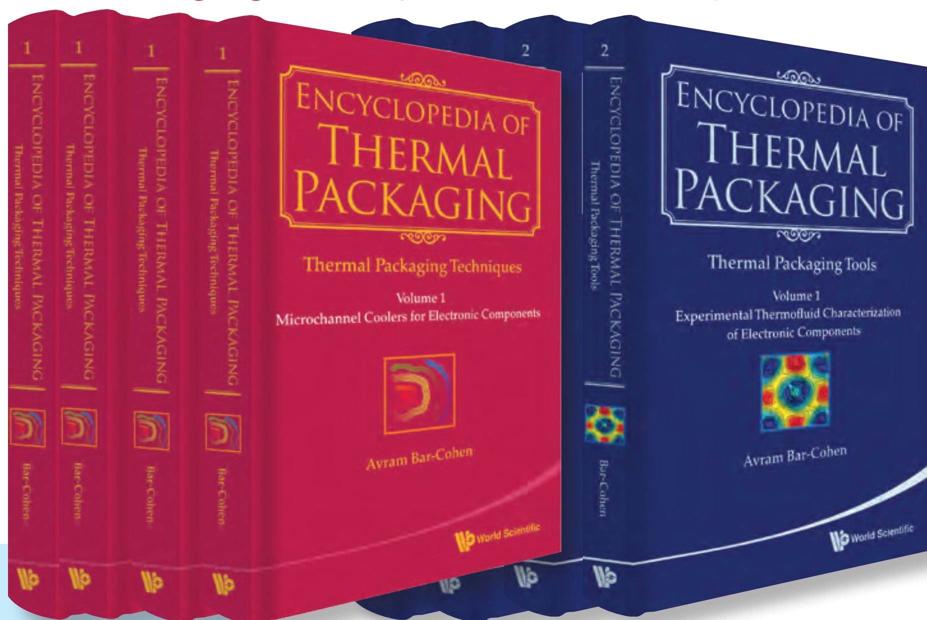
Connecting Great Minds

edited by
Avram Bar-Cohen
(University of Maryland, USA)

Encyclopedia of Thermal Packaging

Set 1: Thermal Packaging Techniques (**A 4-Volume Set**)
Set 2: Thermal Packaging Tools (**A 4-Volume Set**)



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About the Editor-in-Chief

Dr. Avram Bar-Cohen

Dr Avram Bar-Cohen is an internationally recognized leader in thermal science and technology, an Honorary member of ASME, and Fellow of IEEE, as well as Distinguished University Professor in the Department of Mechanical Engineering at the University of Maryland. His publications, lectures, short courses, and research outcomes, as well as professional service in ASME and IEEE, have helped to create the scientific foundation for the thermal management of electronic components and systems and pioneered techniques for energy-efficient sustainable design of manufactured products. His current research focuses on on-chip thermoelectric and two-phase microchannel coolers for high heat flux electronic components, thermal control of solid-state lighting systems, and polymer-fiber composite heat exchangers for seawater applications. Bar-Cohen was the general chair for the 2010 International Heat Transfer Conference in Washington DC and is the President of the Assembly of International Heat Transfer Conferences. He is the Editor-in-Chief of World Scientific Press' forthcoming Encyclopedia of Thermal Packaging. From 2001 to 2010 he served as the Chair of Mechanical Engineering at Maryland and is currently on assignment as a Program Manager in the Microsystem Technology Office at the Defense Advanced Projects Agency in Virginia.

In addition to Honorary membership in ASME, Bar-Cohen's honors include the Luikov Medal from the International Center for Heat and Mass Transfer in Turkey (2008), ASME's Heat Transfer Memorial Award (1999), Curriculum Innovation Award (1999), Edwin F Church Medal (1994) and Worcester Reed Warner Medal (2000), and the Electronic and Electrical Packaging Division's Outstanding Contribution Award (1994) as well as the InterPack Achievement Award (2007). Bar-Cohen was the founding chair of the IEEE Intersociety Conference on Thermal Management in Electronic Equipment (ITHERM) in 1988 and was recognized with the IEEE CPMT Society's Outstanding Sustained Technical Contributions Award (2002), the ASME/IEEE ITHERM Achievement Award (1998) and the THERMI Award from the IEEE/Semi-Therm Conference (1997).

Bar-Cohen has co-authored Design and Analysis of Heat Sinks (Wiley, 1995) and Thermal Analysis and Control of Electronic Equipment (McGraw-Hill, 1983), and has co-edited 14 books in this field. He has authored/co-authored some 350 journal papers, refereed proceedings papers, and chapters in books; has delivered 70 keynote, plenary and invited lectures at major technical conferences and institutions, and he holds 8 US and 3 Japanese patents. He has advised to completion 65 master's and PhD students at the University of Maryland, the University of Minnesota and the Ben Gurion University (Beer Sheva, Israel), where he began his academic career in 1972. From 1998–2001 he directed the University of Minnesota Center for the Development of Technological Leadership and held the Sweatt Chair in Technological Leadership.

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